

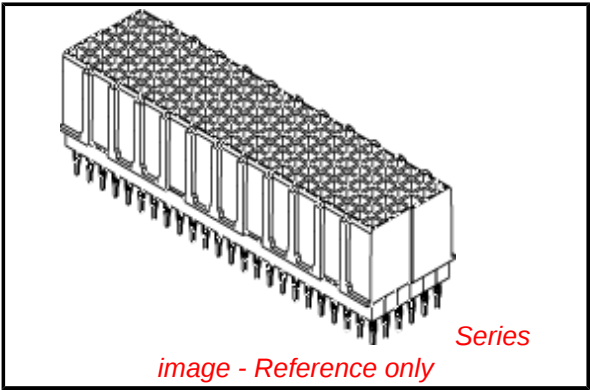
PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0737801244](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 14.00mm (.551"), Pin Length 3.00mm (.118"), Solder Tail

Documents:
[3D Model](#)
[Test Summary \(PDF\)](#)
[Drawing \(PDF\)](#)
[Product Specification PS-73780-999 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

General
Product Family Backplane Connectors
Series [73780](#)
Application Daughtercard, Mezzanine
Comments Solder Tail
Component Type PCB Receptacle
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical
Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.118 In
PC Tail Length (mm) 3.00 mm
PCB Locator No
PCB Retention None
PCB Thickness Recommended (in) 0.063 In
PCB Thickness Recommended (mm) 1.60 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes



EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed



Need more information on product environmental compliance?
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)
Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73780Series](#)

Mates With
HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Temperature Range - Operating

Termination Interface: Style

-55°C to +105°C

Through Hole

Electrical

Current - Maximum per Contact

Data Rate

Real Signals (per 25mm)

Shielded

Voltage - Maximum

15A, 1A

1.0 Gbps

75

No

250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)

Lead-free Process Capability

Max. Cycles at Max. Process Temperature

Process Temperature max. C

5

Wave Capable (TH only)

1

260

Material Info

Reference - Drawing Numbers

Product Specification

Sales Drawing

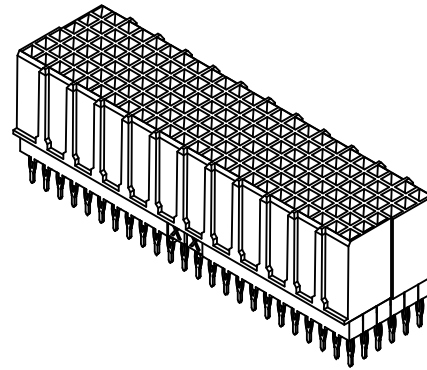
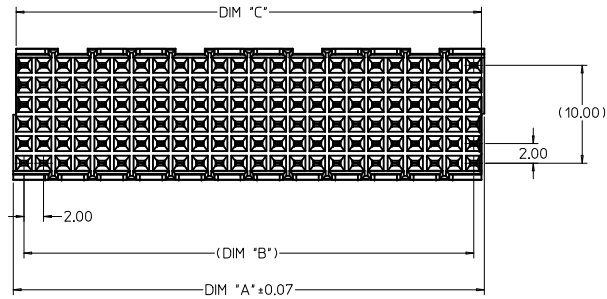
PS-73780-999

SD-73780-004

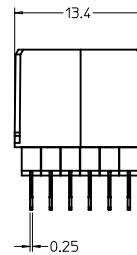
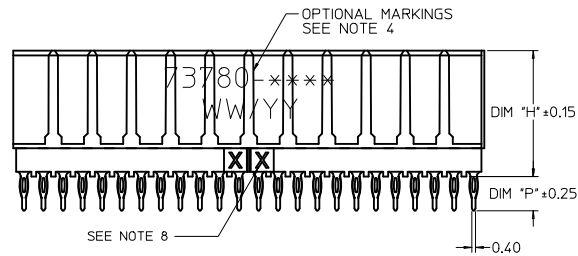
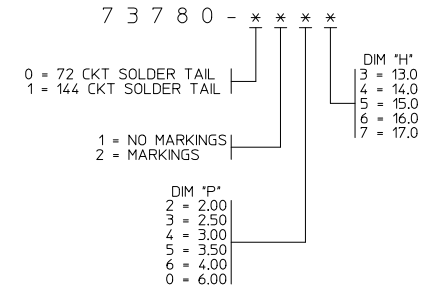
HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION



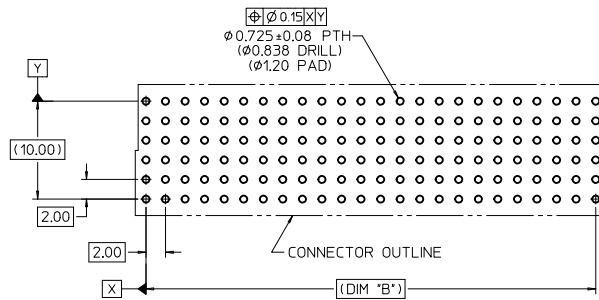
MATERIAL NUMBER ASSIGNMENT



NOTES:

- MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
- FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, .76 MICROMETER MINIMUM THICKNESS, SELECTIVE TIN (Sn), 2.50 MINIMUM THICKNESS ON SOLDER TAILS, NICKEL (Ni) OVERALL.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
- MARKINGS SHOWN FOR REFERENCE ONLY. SEE MATERIAL NUMBER ASSIGNMENT DIAGRAM FOR CORRECT NUMBER. MARKINGS TO INCLUDE MATERIAL NUMBER AND DATE CODE AND CAN BE LOCATED ANYWHERE ON PART, IN ANY ORIENTATION.
- 73780-***7 AND -***0* PARTS TO BE PACKAGED IN TUBES PER PK-70873-0872. ALL OTHER PARTS TO BE PACKAGED IN TUBES PER PK-70873-0900.
- 144-CIRCUIT HDM DAUGHTERCARD STACKING MODULE WITH PRESS-FIT TAILS SHOWN FOR ILLUSTRATION PURPOSES ONLY.
- TRUE POSITION OF PC TAILS IS INSPECTED USING GAUGE NUMBER 73727-0014.
- MARKINGS MAY BE ORIENTED TO EITHER SIDE OF CONNECTOR.

PCB LAYOUT: COMPONENT SIDE



73780-1***	144	48.17	46.00	47.6
73780-0***	72	24.17	22.00	23.6
MATERIAL NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"

UPDATE TO S.T. ONLY IEC NO: UCP2010-1860 DRAWN: JELTON 2010/01/22 CHECKED: CHOKSOMMELLEY 05/07/08 APPROVED: MILLER 2010/02/08	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) DIMENSION STYLE MM ONLY SCALE 4:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	DRAWN BY MIBARRA DATE 05/07/08 CHECKED BY BSMART DATE 05/07/08 APPROVED BY MILLER DATE 2010/02/08	TITLE SALES ASSEMBLY, HDM DAUGHTERCARD STACKING MODULE, SOLDER TAIL MOLEX INCORPORATED MATERIAL NO. SD-73780-004 DOCUMENT NO.	SHEET NO. 1 OF 1